



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC670N25NSFD		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001636644						
<b>Package</b>		PG-TDSON-8-7		<b>Weight*</b>		102.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.192	2.14	2.14	21446	21446
leadframe	non noble metal	iron	7439-89-6	0.038	0.04		370	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		111	
	non noble metal	copper	7440-50-8	37.762	36.94	36.99	369382	369863
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	435	435
encapsulation	organic material	carbon black	1333-86-4	0.094	0.09		918	
	plastics	epoxy resin	-	7.412	7.25		72500	
	inorganic material	silicondioxide	60676-86-0	39.404	38.55	45.89	385446	458864
leadfinish	non noble metal	tin	7440-31-5	1.452	1.42	1.42	14200	14200
plating	noble metal	silver	7440-22-4	0.166	0.16	0.16	1619	1619
solder	noble metal	silver	7440-22-4	0.058	0.06		567	
	non noble metal	tin	7440-31-5	0.046	0.05		454	
	non noble metal	lead	7439-92-1	2.216	2.17	2.28	21676	22697
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		111	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		33	
	non noble metal	copper	7440-50-8	11.320	11.07	11.08	110732	110876
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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